CONNECT

Plasma cleaning utilizing parallel plate plasma cleaning technology.

PSX307 Plasma Cleaner

The PSX307 Plasma Cleaner provides 1.5 times the productivity of conventional plasma cleaners. Panasonic's parallel plate plasma chamber technology delivers superior etch uniformity compared to conventional batch-type plasma cleaner systems.By using an argon plasma treatment, ultra-thin gold-plated electrodes can be wire-bonded reliably without the formation of nickel compounds. The savings achieved in cheaper gold plating can provide the ROI justification alone. The PSX307 Plasma Cleaner's other capabilities include surface modification by oxygen plasma, improving mold resin adhesion and under-fill wettability, and reducing the incidence of peel-off, voids, and cracks.Panasonic's Plasma Monitoring System suppresses abnormal discharges for a secure and efficient production process. The option to include traceability functionality ensures high level process quality as well.

Key Features

Speed - up to 360 substrates/stripes per hour

High productivity - in-line processing for improved bonding, overmolding and underfill

Uniform parallel plate plasma cleaning

Traceability functionality

Ar, O2 or mixed gas plasma possible

PSX307 Plasma Cleaner

Model Number	NM-EFP1A
Cleaning Method	Parallel plate RF back-sputtering method
Gas for electrical discharge	Ar [option: O2]
Substrate dimensions	L 50 x W 20 to L 250 x W 75 incl. S type option; L 50 x W 20 to L 330 x W 120 incl. M type option
Substrate thickness (mm)	0.5 to 2.0
Pneumatic Source	0.49MPa or more, 6.5L/min [A.N.R.]
Power Source	1-phase AC 200V, 2.00kVA [Full Load 5.00kVA] *Compatible with 1-phase 208/220/230/240 V
Dimensions (mm) / Mass	W 930 x D 1100 x H 1450 / 555kg; W 1764 x D 1100 x H 1450 / 850kg incl. S type option; W 1764 x D 1100 x H 1450 / 770kg incl. M type option *Tolerance of equipment dimensions is ±5mm, Touch panel and condition lamp is not included. Mass varies depending on configuration.